

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating						Unit
		MB1L	MB2L	MB4L	MB6L	MB8L	MB10L	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ Fig.1	I _{F(AV)}	0.8						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30						A
Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	60						A
I ² t Rating for fusing (3ms ≤ t ≤ 8.3ms)	I ² t	3.7						A ² S
Typical Junction Capacitance ¹	C _j	7						pF
Typical Thermal Resistance ²	R _{JA}	45						/W
	R _{JC}	15						
	R _{JL}	25						
Operating and Storage Temperature Range	T _j , T _{stg}	-55~+150						

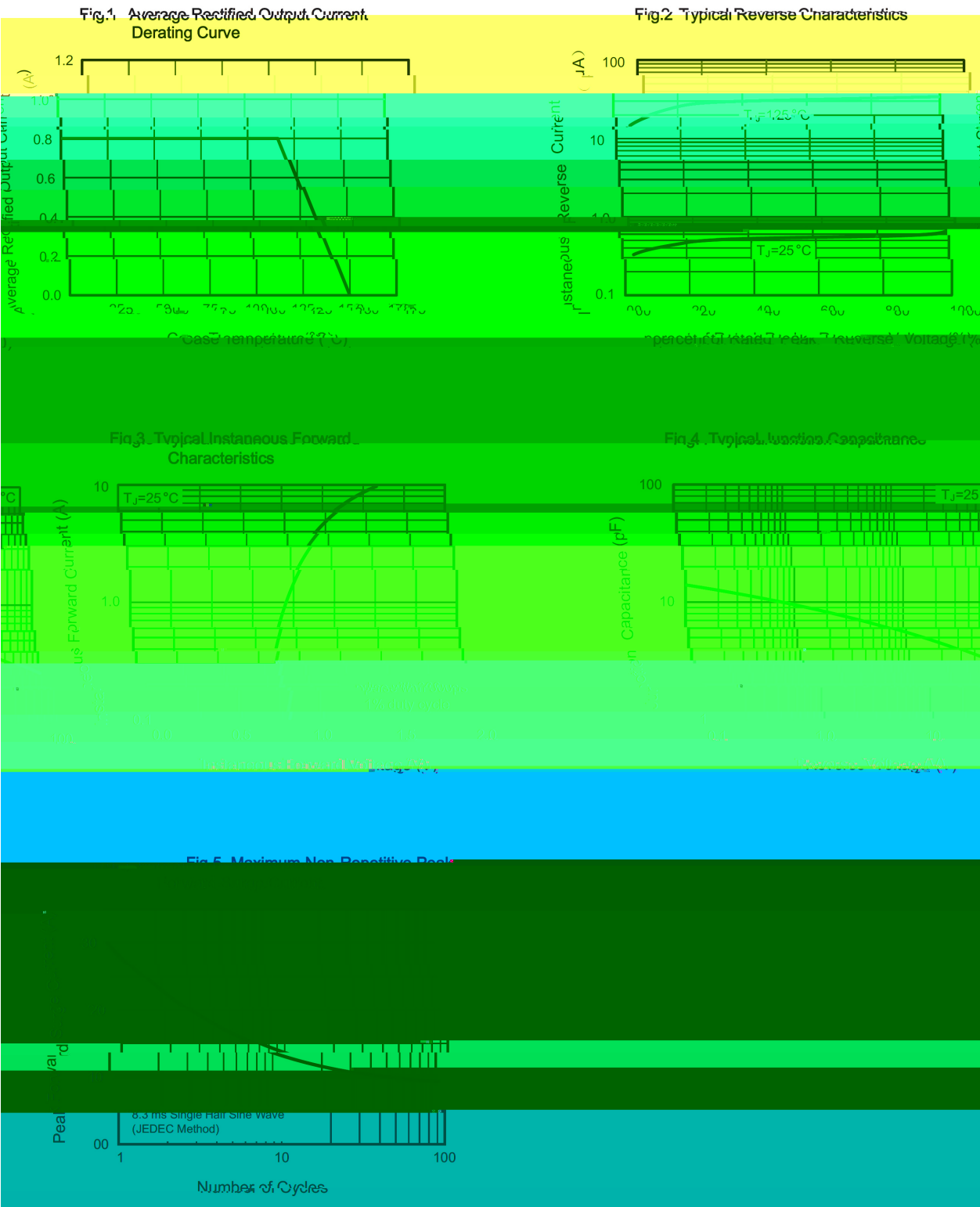
Note:

1. Measured at 1 MHz and applied reverse voltage of 4 V D.C
2. Mounted on glass epoxy PC board with $4 \times 1.5" \times 1.5"$ 3.81×3.81 cm copper pad.

/ Electrical Characteristics(Ta=25)

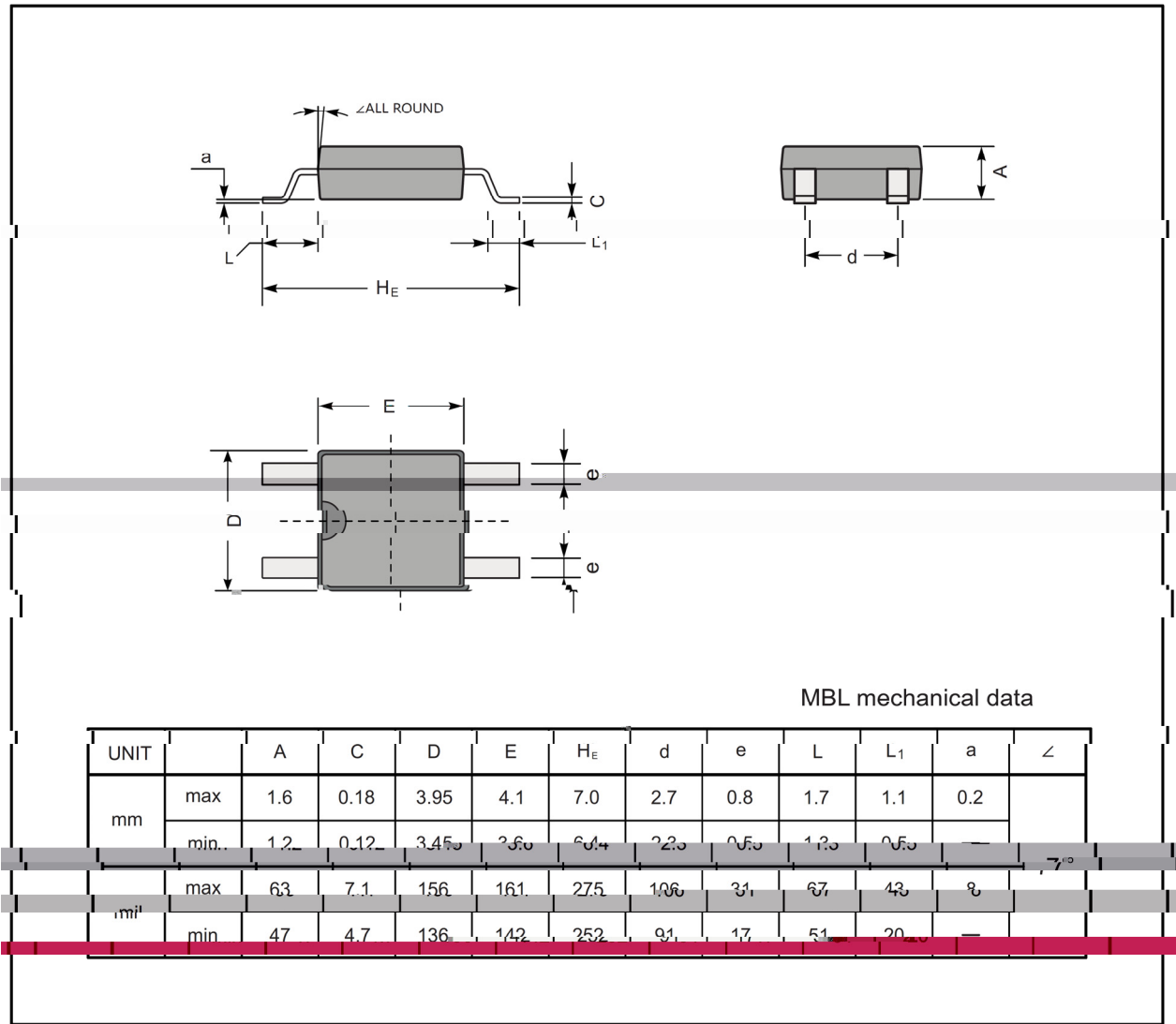
Parameter	Symbol	Test Conditions	Rating	Unit
Max Instantaneous Forward Voltage	V_F	$I_F=0.8A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5	A
		$T_a=125$	100	A

/ Electrical Characteristic Curve

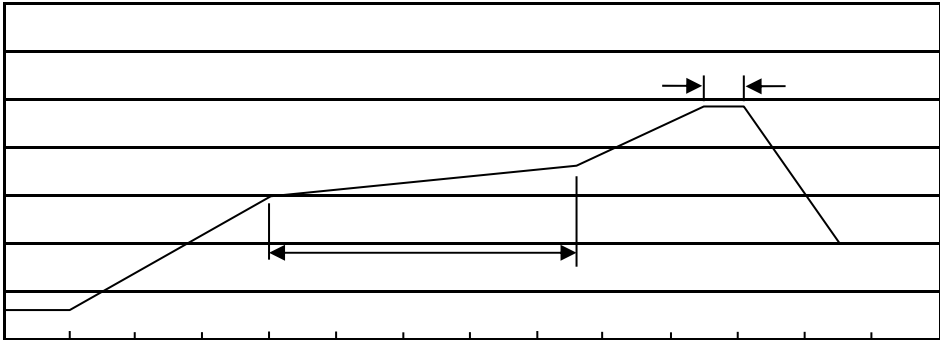


/ Package Dimensions

MBL



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- Note:
- 1

150 180

60 90sec;

2

245±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
MBL	5,000	2	10,000	7	70,000	13 ×12	336×336×40	380×335×366

/ Notices